## **Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings of claims in the application:

## **Listing of Claims:**

1	1. (Original) A method of manufacturing an encapsulated calorimetric
2	flow meter comprising the following steps:
3	providing an integrated circuit assembly incorporating a fluid flow channel, at
4	least two temperature sensing elements operative to measure the temperature in different regions
5	of the channel and a heating element located in between the temperature sensing elements to heat
6	a region of the channel;
7	applying a quantity of gel to the integrated circuit such as to cover at least each
8	end of the channel, thereby forming a gel-covered assembly;
9	inserting the gel-covered assembly into a cavity of a moulding tool ensuring that
10	at least a portion of the gel is in contact with a surface of the cavity;
11	introducing a plastic mould compound into the cavity so as to encapsulate the gel-
12	covered assembly except for the portion in contact with the cavity surface; and
13	removing the assembly from the cavity, whereby there is an opening defined in
14	the plastic mould encapsulating the gel-covered assembly at each end of the channel thus
15	allowing fluid to flow through the channel.
1	2. (Original) A method as claimed in claim 1 wherein the channel is
2	filled with gel before the integrated circuit is encapsulated.
1	3. (Currently Amended) A method as claimed in any preceding claim 1
2	wherein the integrated circuit is mounted on a lead frame.
1	4. (Original) A method as claimed in claim 2 wherein the lead frame has
2	holes which coincide with the end of the channel when the integrated circuit is mounted on the
3	lead frame and the gel is applied so as to cover the holes in the lead frame.

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- 5. (Original) A method as claimed in claim 4 wherein there are slots provided in the lead frame alongside that portion of the lead frame forming a wall of the passageway.
- 1 6. (Original) A method as claimed in claim 5 wherein the slots do not extend past the holes in the lead frame at either end of the passageway.
- 7. (Currently Amended) A method as claimed in any preceding claim 1 wherein the channel is formed by etching.
- 8. (Currently Amended) A method as claimed in any preceding claim 1
  wherein the channel is provided upon a reverse face of the integrated circuit and the temperature
  sensing elements and heat sensing element are provided upon a front face.
  - 9. (Currently Amended) A method as claimed in any preceding claim 1 wherein the integrated circuit is a CMOS integrated circuit.
  - 10. (Currently Amended) A method as claimed in any preceding claim <u>1</u> wherein means are provided to allow direct or wireless communication between the integrated circuit and external circuitry.
  - 11. (Currently Amended) A method as claimed in any preceding claim <u>1</u> wherein the integrated circuit additionally incorporates processing means to calculate a mass flow from the temperature difference detected by the temperature sensing elements.
  - wherein additional circuit elements are incorporated into the integrated circuit, said additional circuit elements including one or more elements selected from: means operative to interface between the heating and sensing means and external electronic control means; means operative to receive and store calibration data for the temperature sensing means; means operative to convert analogue signals to digital signals; include means operative to carry out calculations on

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the digital signals to facilitate improved or additional performance or to improve accuracy or to compensate the measurements for external or internal change; and means provided at the fluid inlet and the fluid outlet such that the errors due to the inlet and outlet temperatures not being equal can be corrected by calculation.